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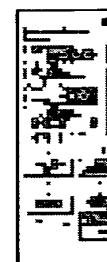


⊕ Title: **JP61078592A2: SILVER SOLDER MATERIAL**

⊕ Country: **JP Japan**

⊕ Kind: **A**

⊕ Inventor: **HOSOI YOSHIHIRO;
DAIGO HIROTO;
KUNITOMO MINOBU;
NARA TAKASHI;**



⊕ Assignee: **KYOCERA CORP
TOKURIKI HONTEN CO LTD**
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⊕ Priority Number: **1984-09-25 JP1984000198614**

⊕ Abstract:

PURPOSE: To obtain a titled material which is excellent in corrosion resistance at the time of use and in a post-treatment process, and also to hold it in sufficient spreading property and wettability by forming a solder material by adding Ge, Pd and Li of a specified quantity to Ag.

CONSTITUTION: A silver solder material is constituted of 0.05W19% Ge, 0.01W10% Pd, 0.01W2% Li, and Ag as a balance. Also, by adding one kind or two kinds or more of Fe, Co and Ni to an Ag-Ge-Pd-Li compound alloy, in case when a base metal of Fe, Co and Ni, and their alloy, for instance, 42 Fe-Ni, covar, stainless steel, etc. has been soldered, the metallic organization is fined and also the soldering strength is improved.

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⊕ INPADOC
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⊕ Family:

PDF	Publication	Pub. Date	Filed	Title
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<input checked="" type="checkbox"/>	JP4038519B4	1992-06-24	1984-09-25	GINROZAI

2 family members shown above

⊕ Other Abstract
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KUNITOMO MINOBI
NARA TAKASHI**

(74) Representative:

(54) SILVER SOLDER MATERIAL

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